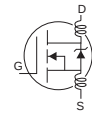


Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	40	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.04	—	V/°C	Reference to 25°C , $I_D = 1mA$
$R_{DS(on)}$	Static Drain-to-Source On-Resis-	—	—	0.008	Ω	$V_{GS} = 10V, I_D = 62A$ ④
		—	—	0.012		$V_{GS} = 4.5V, I_D = 52A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	1.0	—	—	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
g_{fs}	Forward Transconductance	53	—	—	S	$V_{DS} = 25V, I_D = 62A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{DS} = 40V, V_{GS} = 0V$
		—	—	250		$V_{DS} = 32V, V_{GS} = 0V, T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 16V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -16V$
Q_g	Total Gate Charge	—	—	68	nC	$I_D = 62A$
Q_{gs}	Gate-to-Source Charge	—	—	24		$V_{DS} = 32V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	33		$V_{GS} = 4.5V$, See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	—	18	—	ns	$V_{DD} = 20V$
t_r	Rise Time	—	257	—		$I_D = 62A$
$t_{d(off)}$	Turn-Off Delay Time	—	32	—		$R_G = 3.6\Omega, V_{GS} = 4.5V$
t_f	Fall Time	—	64	—		$R_D = 0.4\Omega$, See Fig. 10 ④
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm (0.25in.)
L_S	Internal Source Inductance	—	7.5	—		from package and center of die contact
C_{iss}	Input Capacitance	—	3445	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	1065	—		$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	—	270	—		$f = 1.0MHz$, See Fig. 5



Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	104	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	416		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}, I_S = 62A, V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	—	84	126	ns	$T_J = 25^\circ\text{C}, I_F = 62A$
Q_{rr}	Reverse Recovery Charge	—	223	335	nC	$di/dt = 100A/\mu s$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
 ② $V_{DD} = 15V$, starting $T_J = 25^\circ\text{C}$, $L = 0.18mH$
 $R_G = 25\Omega$, $I_{AS} = 62A$. (See Figure 12)
 ③ $I_{SD} \leq 62A$, $di/dt \leq 217A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$,
 $T_J \leq 175^\circ\text{C}$

④ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

⑤ Calculated continuous current based on maximum allowable junction temperature; for recommended current-handling of the package refer to Design Tip # 93-4

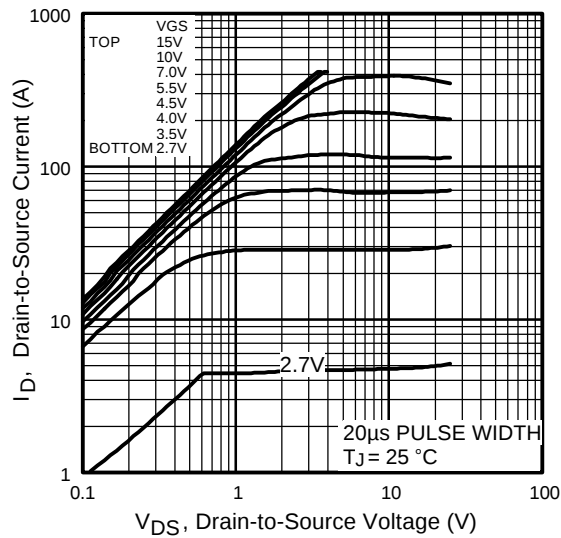


Fig 1. Typical Output Characteristics

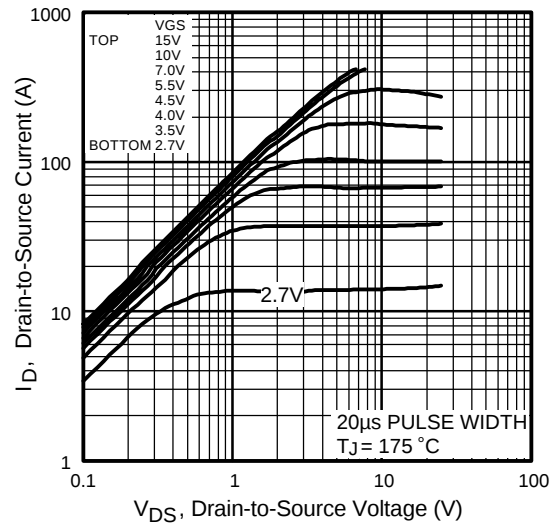


Fig 2. Typical Output Characteristics

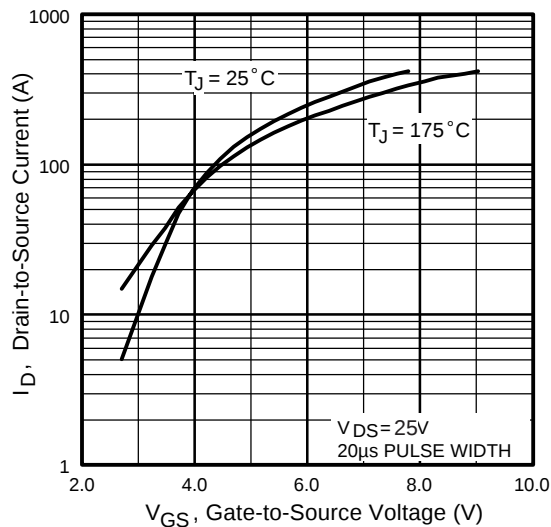


Fig 3. Typical Transfer Characteristics

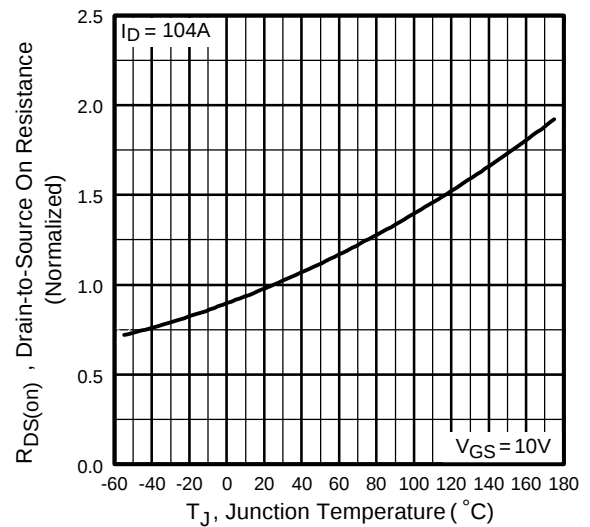


Fig 4. Normalized On-Resistance Vs. Temperature

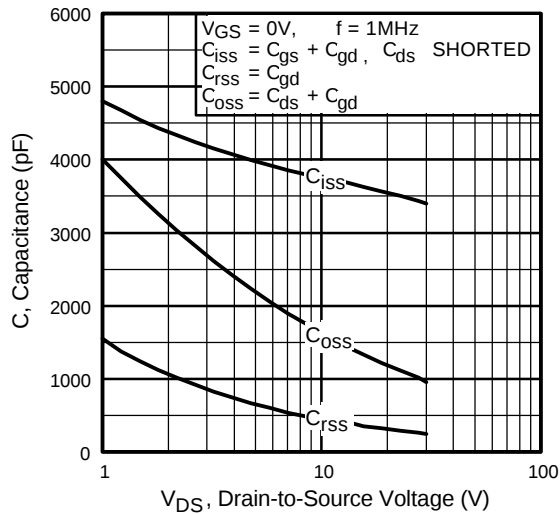


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

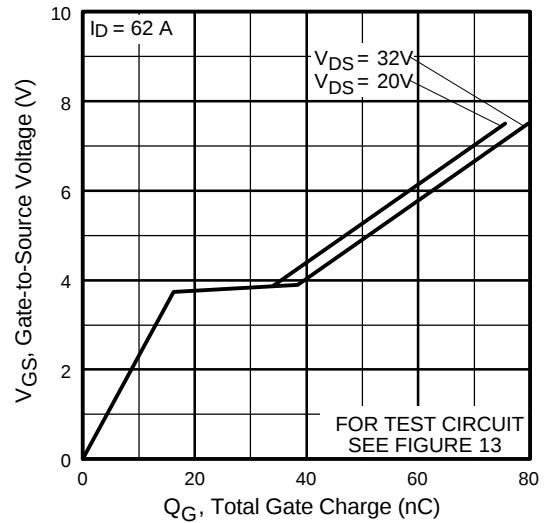


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

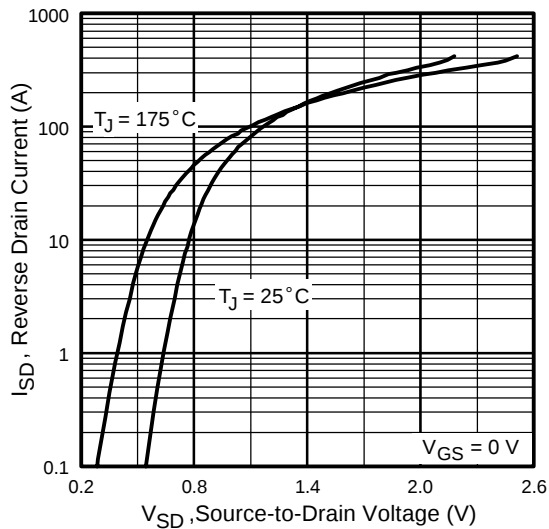


Fig 7. Typical Source-Drain Diode Forward Voltage

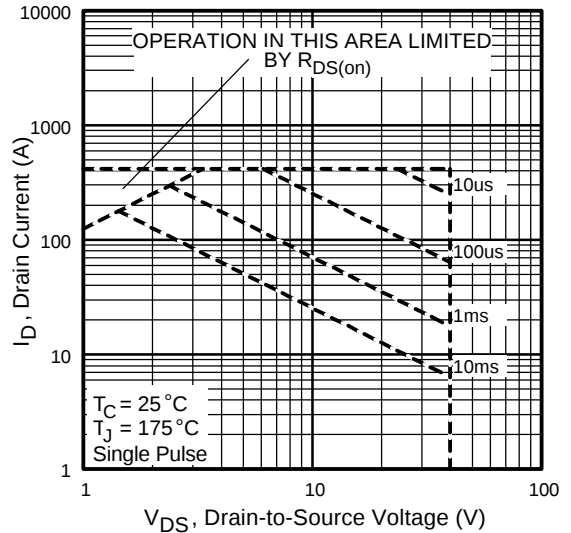


Fig 8. Maximum Safe Operating Area

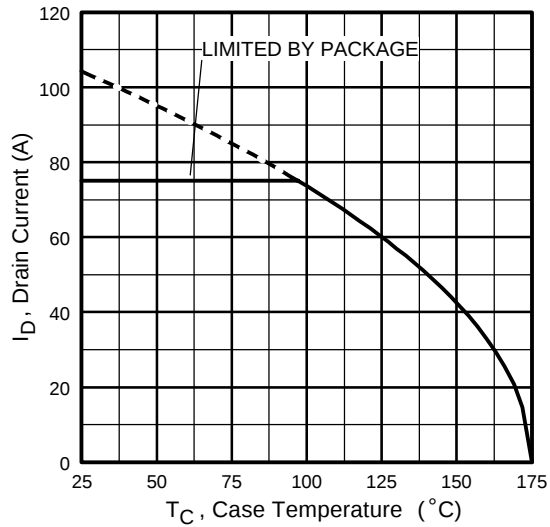


Fig 9. Maximum Drain Current Vs. Case Temperature

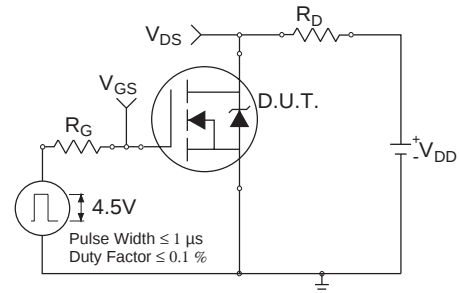


Fig 10a. Switching Time Test Circuit

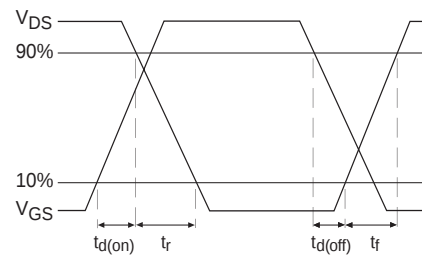


Fig 10b. Switching Time Waveforms

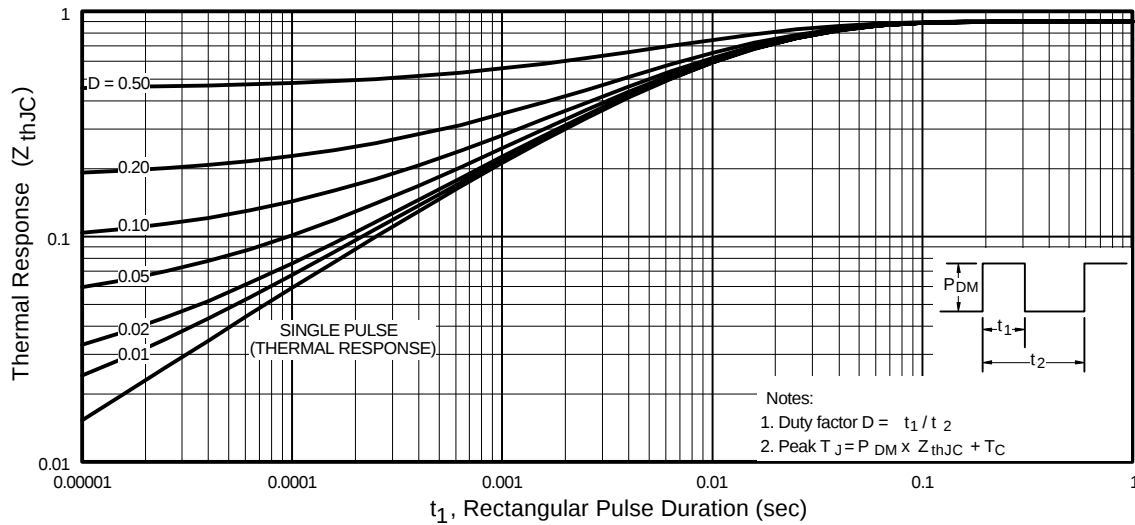


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

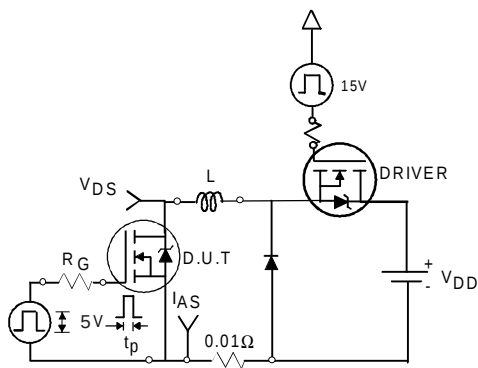


Fig 12a. Unclamped Inductive Test Circuit

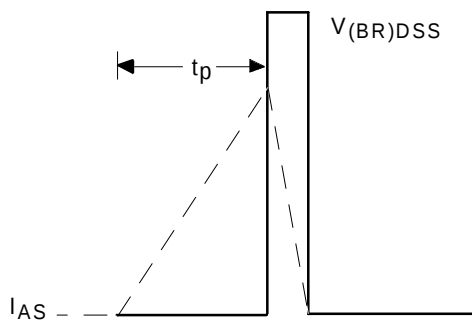


Fig 12b. Unclamped Inductive Waveforms

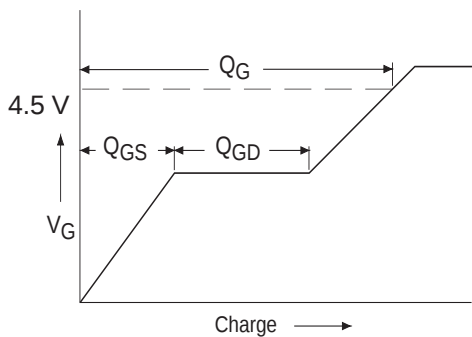


Fig 13a. Basic Gate Charge Waveform

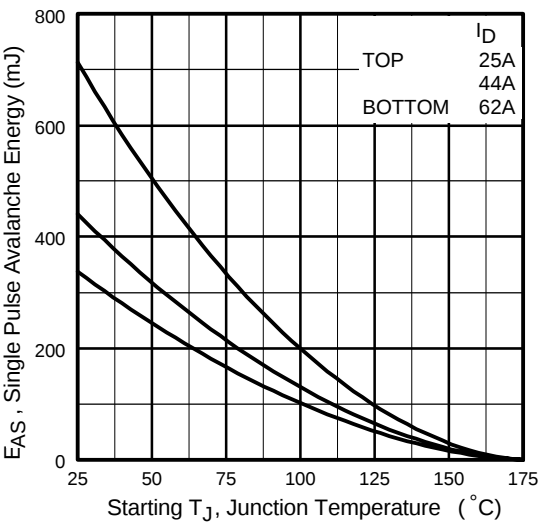


Fig 12c. Maximum Avalanche Energy
Vs. Drain Current

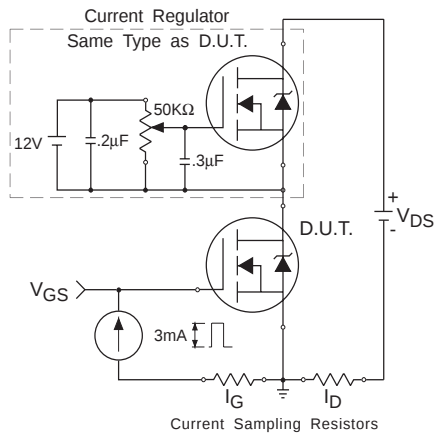


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit

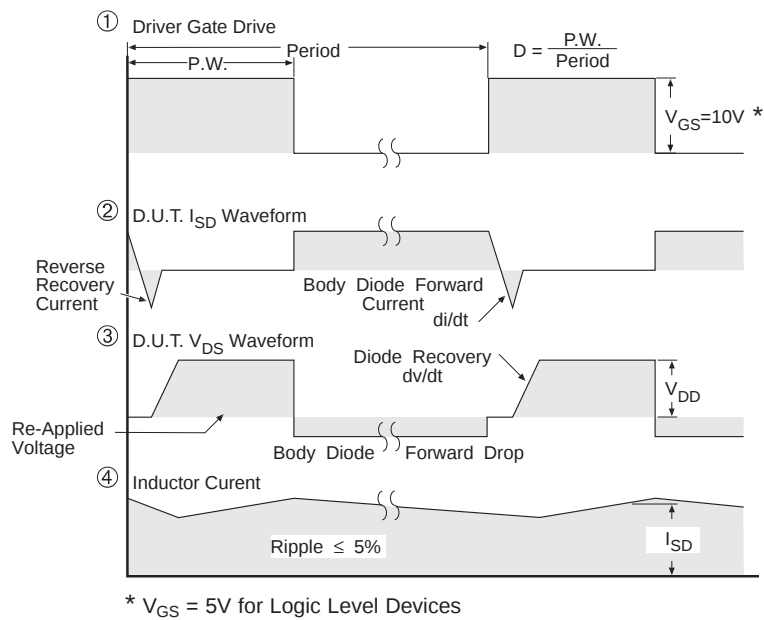
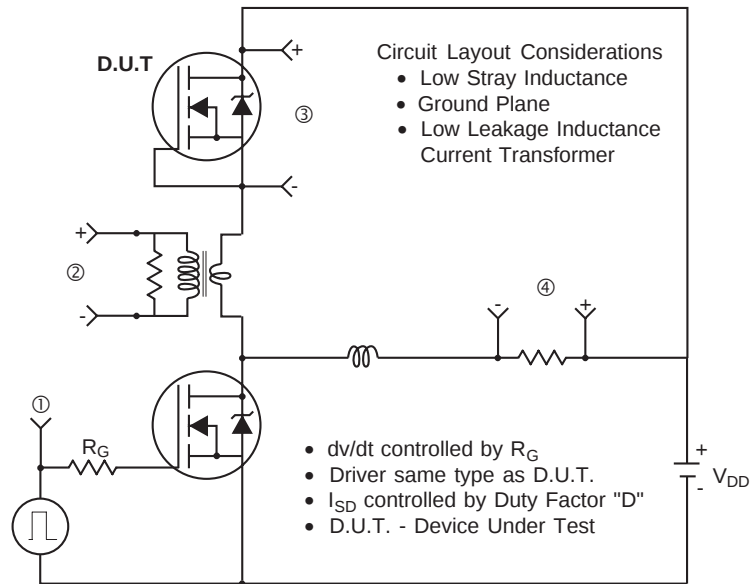
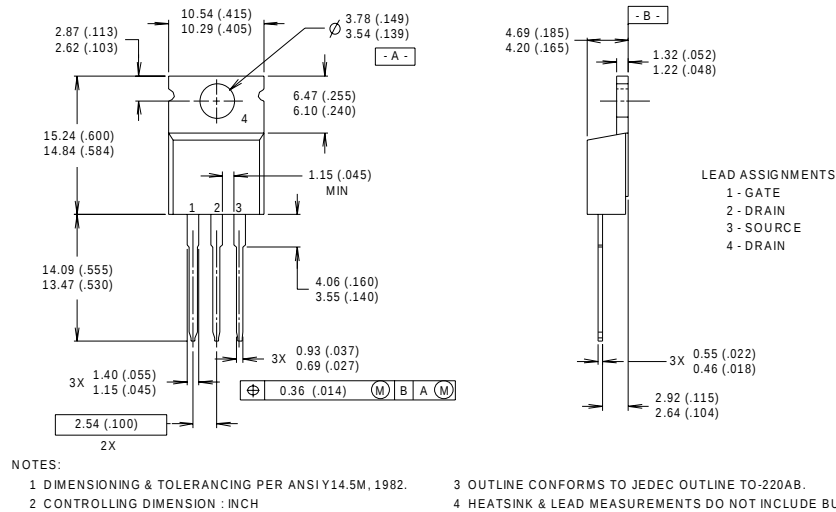


Fig 14. For N-Channel HEXFET® power MOSFETs

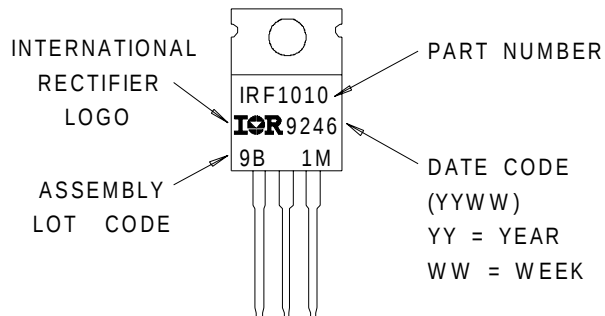
TO-220AB Package Details

Dimensions are shown in millimeters (inches)



TO-220AB Part Marking

EXAMPLE : THIS IS AN IRF1010
WITH ASSEMBLY
LOT CODE 9B1M



International
IR Rectifier

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IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590
IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111
IR JAPAN: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo Japan 171 Tel: 81 3 3983 0086
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<http://www.irf.com/> Data and specifications subject to change without notice. 10/99

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Note: For the most current drawings please refer to the IR website at:
<http://www.irf.com/package/>